

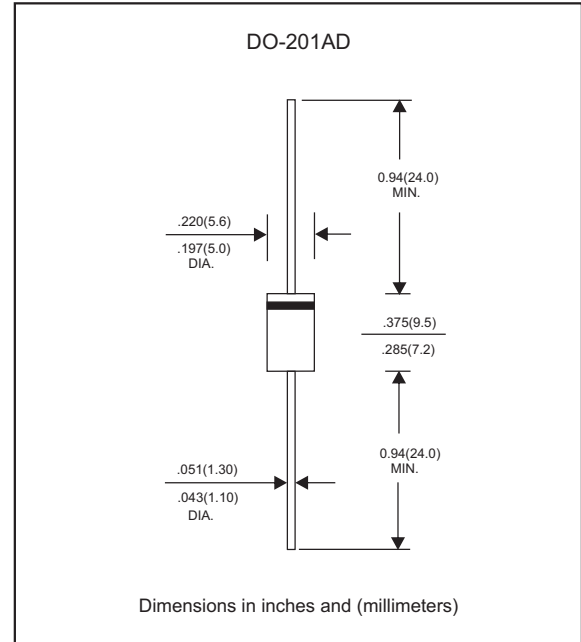
### Features

- Low reverse leakage current
- Low forward drop down voltage & high current capability
- High surge current capability
- Super fast switching speed for high efficiency
- Glass passivated chip junction
- High Reliability
- Lead-free parts for green partner, meet RoHS requirements
- Suffix "-H" indicates Halgon free parts, ex. SF51G-H.

### Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, DO-201AD
- Lead : Axial leads, solderable per MIL-STD-202, Method 208 guaranteed
- Polarity: Color band denotes cathode end
- Mounting Position : Any

### Package outline



### Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	Ambient temperature = $55^\circ\text{C}$	$I_o$			5.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	$I_{FSM}$			150	A
Reverse current	$V_R = V_{RRM} \quad T_J = 25^\circ\text{C}$	$I_R$			5.0	$\mu\text{A}$
	$V_R = V_{RRM} \quad T_J = 125^\circ\text{C}$				100	
Thermal resistance	Junction to ambient	$R_{\theta JA}$		30		$^\circ\text{C}/\text{W}$
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	$C_J$		80		pF
Storage temperature		$T_{STG}$	-65		+175	$^\circ\text{C}$

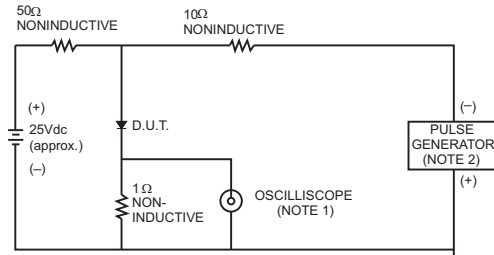
SYMBOLS	$V_{RRM}^{*1}$ (V)	$V_{RMS}^{*2}$ (V)	$V_R^{*3}$ (V)	$V_F^{*4}$ (V)	$t_{rr}^{*5}$ (ns)	Operating temperature $T_J$ ( $^\circ\text{C}$ )
SF51G	50	35	50	0.95	35	-55 to +150
SF52G	100	70	100			
SF53G	150	105	150			
SF54G	200	140	200			
SF55G	300	210	300	1.25		
SF56G	400	280	400			
SF57G	500	350	500	1.70		
SF58G	600	420	600			

- \*1 Repetitive peak reverse voltage
- \*2 RMS voltage
- \*3 Continuous reverse voltage
- \*4 Maximum forward voltage@ $I_F=5.0\text{A}$
- \*5 Maximum Reverse recovery time, note 1

Note 1. Reverse recovery time test condition,  $I_F=0.5\text{A}$ ,  $I_R=1.0\text{A}$ ,  $I_{RR}=0.25\text{A}$

**Rating and characteristic curves**

FIG.1- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm.22pF.  
2. Rise Time= 10ns max., Source Impedance= 50 ohms.

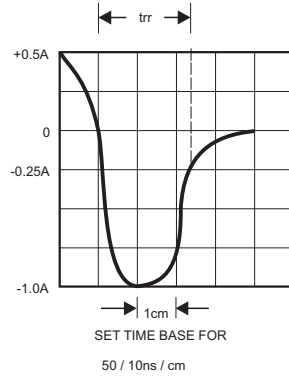


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

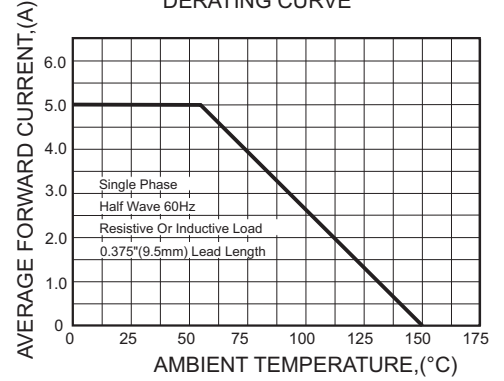


FIG. 3 - TYPICAL FORWARD CHARACTERISTICS

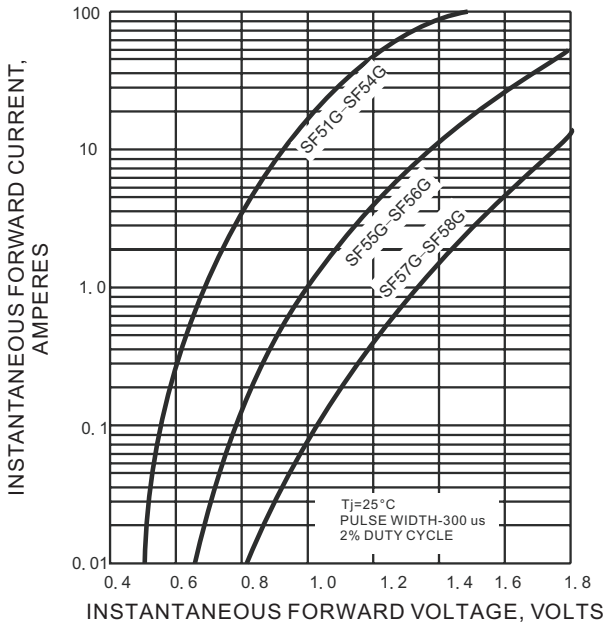


FIG.4-TYPICAL REVERSE CHARACTERISTICS

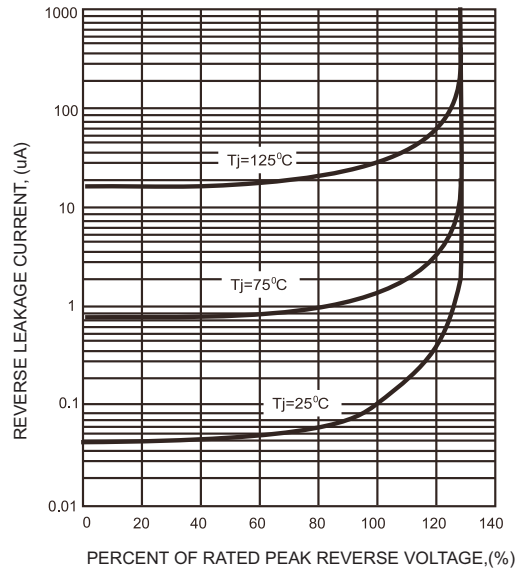


FIG.5-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

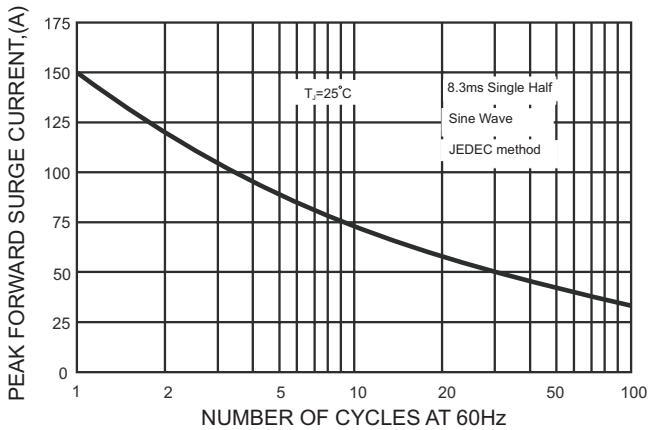
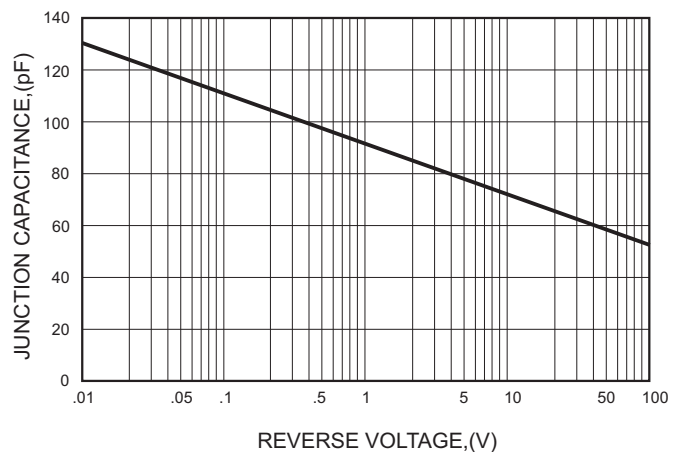




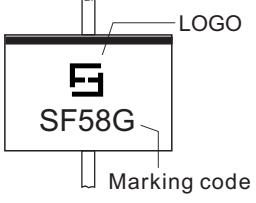
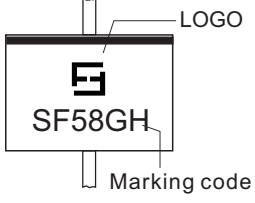
FIG.6-TYPICAL JUNCTION CAPACITANCE



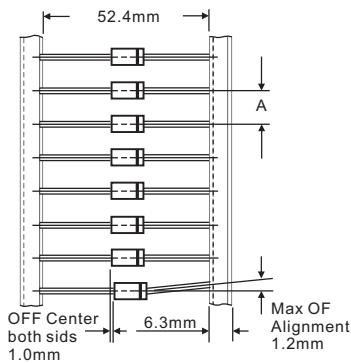
**Pinning information**

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

**Marking**

Type number	Marking code	Example	
SF51G	SF51G	For Halogen Device 	For Halogen-free Device 
SF52G	SF52G		
SF53G	SF53G		
SF54G	SF54G		
SF55G	SF55G		
SF56G	SF56G		
SF57G	SF57G		
SF58G	SF58G		

**Taping specifications for AXIAL devices**



**AMMO PACKING**

DEVICE CASE TYPE	Q'TY 1 (PCS / BOX)	INNER BOX SIZE (m/m)	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
DO-201AD	1,250	258 * 75 * 143	405 * 270 * 320	12,500	14.0

**Suggested thermal profiles for soldering processes**

1. Lead free temperature profile wave-soldering

